

MAX KOSCHMEDER

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SUMMARY

Positive, responsible, team orientated mechanical engineer seeking a challenging manufacturing or process engineering position to utilize my strong technical & hands-on approach to creative and effective problem solving.

TECHNICAL SKILLS

- ÿ Mechanical assembly design/development
- ÿ Manufacturing process development and integration
- ÿ Operator training & Process instructions
- ÿ Effective customer interaction to resolve issues, drive quality improvements
- ÿ Excellent communicator
- ÿ Strong and creative problem solver
- ÿ Process and equipment implementation, optimization and troubleshooter
- ÿ Team coordination and multitasking
- Dedication and personal integrity
- Catia V5, SolidWorks, Pro-E
- MS Excel, Project, Word

INTELLECTUAL PROPERTY ACTIVITY:

- ÿ Five U.S. patents and seven IBM technical disclosures, related to computer system layout and cooling, PCBA latching, heatsink grounding, laser wire striping, slider bonding, EMC grounding and shielding.

WORK EXPERIENCE

Mechanical Packaging Integration Advisory Engineer, IBM, Rochester, MN (1/2007 - present).

Responsible for development project coordination, design and classical test. Ensured product met: UL-CSA safety/standards, electromagnetic compatibility (EMC), thermal, structural and materials requirements. Supported CAD/release, supplier logistics, procurement, manufacturing, shipping packaging/fragility and others. Used strong manufacturing background to ensure design for manufacturability. Some bid and proposal activity for follow-on development projects also included.

- ÿ Packaged IBM CELL processor module into a PCI based graphics accelerator card. Member of team that developed cooling concept; **submitted for U.S. patent**. Product released ahead of schedule and within cost constraints.

Current Products Lead Engineer, IBM, Rochester, MN (12/2004 - 12/2006).

Responsible for development engineering support to resolve manufacturing issues of current shipping computer products.

- ÿ Interfaced with manufacturing, suppliers & procurement to implement engineering changes quickly so as to maintain production yet minimize scrap.
- ÿ Successfully implemented product environmental regulations (European WEEE, RoHS, Chinese EIP) across four IBM sites including designing & releasing product labels & structures.

Mechanical Development Lead Engineer, IBM, Rochester, MN (11/1993 - 11/2004).

Responsible for design of frame, card cage and card book hardware. Developed hardware to meet classical test requirements. Supported CAD/release, procurement, manufacturing and others. Used strong manufacturing background to ensure design for manufacturability.

- ÿ Internal mechanical hardware development team lead for mid and high end AS/400 and RS/6000 computers. Developed card hardware for BlueGene/L supercomputer. Released on time; Successfully installed 64 rack system at Lawrence Livermore National Lab.
- ÿ Developed printed circuit board hardware, heatsinks, stiffener and eject latches. Received U.S. patent on a low profile, high leverage eject latch.

- ÿ Led a design team to develop a slide-out card cage to include a processor card, memory cards and I/O cards. Products released on time and within usability and cost constraints. **Received U.S. patent on the latching of the processor card assembly.**

Manufacturing Process Lead Engineer, IBM, Rochester, MN (6/1989 - 10/1993).

Responsible for key processes of state-of-the-art automated assembly of hard disk drive head suspension assembly processes.

- ÿ Developed prototype semi-automated production processes: pulsed CO₂ laser wire stripping; cyanoacrylate slider bonding; and wire tack adhesive dispense/UV cure. This improved quality and yields as compared to the manual line and provided insight of the required integration for a fully automated line.
- ÿ Engaged equipment suppliers to design and develop automated stations within high volume, fully automated production line. Released first automated line to production on schedule and above expected throughput.
- ÿ Continued to optimize processes and hardware to reduce “takt” time for maximum line throughput and increase yields.
- ÿ Supported replication, installation, qualification and maintenance training of four automated production lines. Lines released within time, usability, cost and quality constraints.
- ÿ Supported transfer of automated production lines to IBM San Jose. **Received Formal team recognition for re-qualifying the lines ahead of schedule and at higher yields.**

Manufacturing Process Engineer, IBM, Rochester, MN (12/1983 - 6/1989).

Responsible for various hard disk drive Read/Write recording head manufacturing processes.

- ÿ Maintained and enhanced manufacturing line processes and equipment: ferrite glass bonding, laser scribe product serialization, associated cleaning systems and ferrite epoxy bonding. Improved process flow to reduce cycle time and improve quality.
- ÿ Developed SiO sputter deposition process to replace SiO evaporative deposition resulting in higher production rates and yields using reconditioned surplus equipment.
- ÿ Implemented statistical process control (SPC), conducted gage capability and process capability studies in the manufacturing area to qualify new tools and processes as well as improving stable manufacturing yields.

Pre-professional Experience Summary:

- ÿ Performed manufacturing assembly and machining operations as a Mechanical Engineer trainee at Rathgeber GMBH, Munich, Germany (6/1983 - 8/1983)
- ÿ Recorded and evaluated (Fourier) process pipeline vibration data as a summer Engineering intern at Fisher Controls, Marshalltown, IA (6/1982 - 8/1982)

EDUCATION

- ÿ Bachelor of Science in Mechanical Engineering, Iowa State University (12/1983)

COMMUNITY

- National Engineers Week presenter at Pine Island Public School since 2001
- Volunteer with United Way Olmsted County, MN